

Final Product Change Notification

201610016F11 : Introduction of Quad Source for Leadless HVSON8

Product TJA1051TK/3

Note: This notice is NXP Company Proprietary.

Issue Date: May 17, 2023 Effective date: Aug 15, 2023

Management summary

Introduction of Quad Source for leadless HVSON8 product TJA1051TK(/3) Change Category

Wafer Fab Process	Assembly Process	Product Marking	Test Process	Design
WaferFabMaterials	C Assembly Materials	Mechanical Specification	□ Test Equipment	🗆 Errata
Wafer Fab Location	Assembly Location Other	Packing/Shipping/Labeling	Test Location	Electrical spec./Test coverage

PCN Overview

Description

As part of the NXP Business Continuity Management (BCM) program NXP's Product Line In-Vehicle Networking (PL IVN) introduces a quad-sourcing strategy, extending its current dual source front-end waferfab diffusion with dual source back-end assembly, final test and packing/shipping/labeling. This continues NXP's Global Business Continuity Management process to establish an industrial base that is agile, robust and can reliably service the long term forecasted market growth of IVN products. The High Speed CAN transceiver product TJA1051TK/3 in leadless HVSON8 package will be quad-sourced. To this end, assembly, final test and packing/shipping/labelling will start in a 2nd location

ASEN, Suzhou, China (ATX-SZ), next to the current site ATBK, Bangkok, Thailand.

Quad source means that a product can be:

- diffused in either waferfab ICN8, Nijmegen, the Netherlands or SSMC, Singapore

- assembled, final tested and packed/shipped/labeled in either assembly site ATBK, Bangkok, Thailand, or ASEN, Suzhou, China

The actual sourcing is at NXP's discretion.

This change does not affect the currently released NXP 12NC product part numbers for TJA1051TK/3. New12NCs have been created to make use of the Quad Source.

In the attachment to this Product Change Notification (PCN) details of the changes involved are given, as well as four additional documents:

- The AEC-Q100 qualification results for the release of ASEN assembly

- A release report for ASEN Final Test (FT)

- The applicable ZVEI Delta Qualification Matrix (DeQuMa) for the assembly transfer, both in zipped excel and pdf format

See the paragraphs 'Additional information' and 'Remarks' below for instructions on how to obtain these documents. Attached to this e-mail is an excel file with two sheets. One contains the sales history for your affected part numbers, the other the product change list. In both sheets reference is made to new part number, orderable part number and NXP 12NC code. In case you want to make use of the Quad Source you need to order this new part number.

Reason

NXP has the responsibility to have appropriate processes and procedures in place to ensure the ability to continue business operations in the event of an interruption affecting all or part(s) of the NXP organization. NXP has a Business Continuity Management (BCM) program in place since 2010. The BCM program includes 3 elements:

- 1. Risk Management per site
- 2. Contingency on Product level
- 3. Supplier Risk management.

This PCN refers to the 2nd element "Contingency on product level" which includes also the Quad Source option.

The second reason for creating a Quad Source is to establish an industrial base able to support the ever-increasing demand for NXP A-BCD3 products, driven by longer term growth in the In-Vehicle Networking market.

It has been decided to establish a Quad Source for leadless HVSON8 product TJA1051TK/3. This means that this product, which is currently assembled, final tested and packed/shipped/labeled in ATBK, Bangkok, Thailand, will also be assembled, final tested and packed/shipped/labeled in ASEN, Suzhou, China.

Identification of Affected Products

Top Side Marking

In the attachment to this PCN it is shown how the product name and the marking changes.

Product Availability

Sample Information Samples are available upon request Production Planned first shipmentAug 17, 2023

Anticipated Impact on Form, Fit, Function, Reliability or Quality

There is no impact to the product's functionality.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

The current products are not affected by this change. We will merely add a back-end assembly, final test and packing/shipping/labeling Dual Source, creating a true Quad Source under new NXP 12NC product part numbers.

Additional information

Self qualification:<u>view online</u> Additional documents: view online

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Jun 16, 2023.

Remarks

Please use the link 'view online' under the heading 'Additional information' above, to log in to the NXP e-PCN system you're subscribed to, in order to obtain the attached document with relevant detailed information from the tab 'Files'.

Should you not be able to obtain this document, please contact your NXP sales representative or the e-mail address mentioned below under 'Contact and Support'.

Related Notification

Notification	lssue Date	Effective Date	Title
201610016A	Dec 05 2016	,	Introduction of Quad Source
201610016F03	Feb 13, 2019	May 14, 2019	Introduction of Quad Source for Product TJA1051

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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